L Number	Hits	Search Text	DB	Time stamp
1	2	5291061.pn.	USPAT;	2004/09/29
		•	US-PGPUB;	23:00
			EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	1 2004 (00 (00
2	1		USPĀT	2004/09/29 22:59
3	1		USPAT	2004/09/29
	_		001111	22:59
4	1		USPAT	2004/09/29
1_				22:59
5	1		USPAT	2004/09/29
6	1		USPAT	23:00 2004/09/29
"			OSFAI	23:00
7	2	5323060.pn.	USPAT;	2004/09/29
		_	US-PGPUB;	23:01
			EPO; JPO;	
			DERWENT;	
8	2	5502289.pn.	IBM_TDB USPAT;	2004/09/29
			US-PGPUB;	23:02
			EPO; JPO;	
			DERWENT;	
		5701450	IBM_TDB	0004/00/00
9	2	5721452.pn.	USPAT; US-PGPUB;	2004/09/29 23:03
			EPO; JPO;	23.03
			DERWENT;	
			IBM_TDB	
10	1		USPAT	2004/09/29
11	1		USPAT	23:03 2004/09/29
	<u> </u>		USPAI	23:03
12	1		USPAT	2004/09/29
				23:03
13	2	5815372.pn.	USPAT;	2004/09/29
			US-PGPUB; EPO; JPO;	23:04
			DERWENT;	
			IBM_TDB	
14	2	5886412.pn.	USPAT;	2004/09/29
			US-PGPUB;	23:05
			EPO; JPO; DERWENT;	
			IBM TDB	
15	2	5963794.pn.	USPĀT;	2004/09/29
			US-PGPUB;	23:06
			EPO; JPO; DERWENT;	
			IBM TDB	
16	2	6005778.pn.	USPAT;	2004/09/29
		-	US-PGPUB;	23:34
			EPO; JPO;	
			DERWENT;	
17	1		IBM_TDB USPAT	2004/09/29
				23:06
18	1		USPAT	2004/09/29
19	1		HCDAM	23:06
19	1	4	USPAT	2004/09/29
20	1		USPAT	2004/09/29
				23:07
21	1		USPAT	2004/09/29
22	1		USPAT	23:07 2004/09/29
	•		UDIAI	23:07

23	1		USPAT	2004/09/29
				23:07
24	1		USPAT	2004/09/29
				23:07
25	1		USPAT	2004/09/29
1				23:07
26	1		USPAT	2004/09/29
	1			23:08
27	1		USPAT	2004/09/29
				23:08
28	3671212	(substrate carrier board pcb cb (printed	USPAT;	2004/09/29
		adj4 board))	US-PGPUB;	23:34
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
29	2598502	semiconductor die chip dice ic	USPAT;	2004/09/29
	2030002	(integrated adj circuit)	US-PGPUB;	23:35
		(Integrated day officially	EPO; JPO;	23.33
			DERWENT;	
			IBM TDB	
30	197831	(semiconductor die chip dice ic	USPAT;	2004/09/29
30	197031	(integrated adj circuit)) with (stack		23:36
	1	stacking stacked level multiple)	US-PGPUB;	23:36
ł		stacking stacked level multiple)	EPO; JPO;	
			DERWENT;	
31	149888	/aominanduatan dia ahin dia dia	IBM_TDB	0004/00/00
31	149000	(semiconductor die chip dice ic	USPAT;	2004/09/29
		(integrated adj circuit)) with (stack	US-PGPUB;	23:38
		stacking stacked level)	EPO; JPO;	1
			DERWENT;	
32	38688	(manufacture de la califacture de la califactur	IBM_TDB	
32	30000	(semiconductor die chip dice ic	USPAT;	2004/09/29
		(integrated adj circuit)) with (stack	US-PGPUB;	23:39
	1	stacking stacked)	EPO; JPO;	
			DERWENT;	
1 22	1	[, , , , , , , , , , , , , , , , , , ,	IBM_TDB	
33	18244	((substrate carrier board pcb cb (printed	USPAT;	2004/09/29
}		adj4 board))) same ((semiconductor die	US-PGPUB;	23:39
]		chip dice ic (integrated adj circuit))	EPO; JPO;	
1		with (stack stacking stacked))	DERWENT;	
124	1111		IBM_TDB	
34	1113	(((substrate carrier board pcb cb	USPAT;	2004/09/29
		(printed adj4 board))) same	US-PGPUB;	23:41
		((semiconductor die chip dice ic	EPO; JPO;	
		(integrated adj circuit)) with (stack	DERWENT;	
]	1	stacking stacked))) same (adhesive	IBM_TDB	
l	l	adhesion)		